

Abstract

[Problem to be solved] Provided is a treatment liquid and a cleaning method for removing ruthenium and tungsten adhering to an edge surface portion and a back surface portion of a semiconductor wafer.

[Solution] A treatment liquid for cleaning a semiconductor wafer is a treatment liquid containing (A) a hypochlorite ion and (C) a solvent, in which pH at 25°C is more than 7 and less than 12.0. A method for removing ruthenium and tungsten from a semiconductor wafer and cleaning the semiconductor wafer by bringing the treatment liquid into contact with the semiconductor wafer containing ruthenium or tungsten is provided.

[No Figure]